

Thyristor Module

=2x 800 V

60 A

 V_{τ} 1.24 V

Phase leg

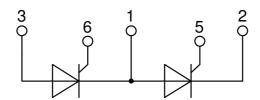
Part number

MCC56-08io8B



Backside: isolated





Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al2O3-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-240AA

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- · Reduced weight
- Advanced power cycling

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

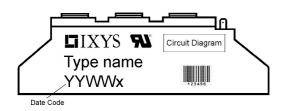
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	r	• ""		Ì	Ratings □.		
Symbol	Definition	Conditions	T 0500	min.	typ.	max.	Uni
V _{RSM/DSM}	max. non-repetitive reverse/forwa		$T_{VJ} = 25^{\circ}C$			900	\
V _{RRM/DRM}	max. repetitive reverse/forward bl		$T_{VJ} = 25^{\circ}C$			800	٧
I _{R/D}	reverse current, drain current	$V_{R/D} = 800 \text{ V}$	$T_{VJ} = 25^{\circ}C$			200	μΑ
.,		V _{R/D} = 800 V	T _{VJ} = 125°C			5	mA
V _T	forward voltage drop	$I_T = 100 A$	$T_{VJ} = 25^{\circ}C$			1.26	٧
		$I_T = 200 \text{ A}$				1.57	٧
		$I_T = 100 A$	$T_{VJ} = 125$ °C			1.24	٧
	, , , , , , , , , , , , , , , , , , , ,	I _T = 200 A				1.62	٧
I _{TAV}	average forward current	$T_c = 85^{\circ}C$	$T_{VJ} = 125^{\circ}C$			60	Α
T(RMS)	RMS forward current	180° sine				94	Α
V_{T0}	threshold voltage } for power lo	oss calculation only	$T_{VJ} = 125$ °C			0.85	٧
r _T	slope resistance					3.7	mΩ
R _{thJC}	thermal resistance junction to cas	e				0.45	K/W
R _{thCH}	thermal resistance case to heatsi	nk			0.20		K/W
P _{tot}	total power dissipation		$T_{C} = 25^{\circ}C$			222	W
I _{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			1.50	k٨
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1.62	k٨
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 125$ °C			1.28	k₽
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			1.38	k/
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			11.3	kA ² s
		t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			10.9	kA ² s
		t = 10 ms; (50 Hz), sine	$T_{VJ} = 125$ °C			8.13	kA ² s
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			7.87	kA2s
C _J	junction capacitance	$V_R = 400 V$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		74		рF
P _{GM}	max. gate power dissipation	t _P = 30 μs	T _C = 125°C			10	W
		$t_P = 300 \mu s$				5	W
P_{GAV}	average gate power dissipation					0.5	W
(di/dt) _{cr}	critical rate of rise of current	$T_{VJ} = 125 ^{\circ}\text{C}; f = 50 \text{Hz}$ re	epetitive, $I_T = 150 \text{ A}$			150	A/μs
		$t_P = 200 \mu s; di_G/dt = 0.45 A/\mu s; -$					<u> </u>
		$I_G = 0.45 A; V = \frac{2}{3} V_{DRM}$	on-repet., $I_T = 60 \text{ A}$			500	A/μs
(dv/dt) _{cr}	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	T _{VJ} = 125°C			1000	V/µs
		R _{GK} = ∞; method 1 (linear volta	ge rise)				
V _{GT}	gate trigger voltage	V _D = 6 V	$T_{VJ} = 25^{\circ}C$			1.5	٧
.		<u> </u>	$T_{VJ} = -40$ °C			1.6	٧
I _{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			100	mA
. .			$T_{VJ} = -40$ °C			200	mA
V _{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	T _{vJ} = 125°C			0.2	٧
I _{GD}	gate non-trigger current	D DNW	VO			10	mA
I _L	latching current	t _p = 10 μs	T _{vJ} = 25°C			450	mA
·L	atomig carrent	$I_{\rm G} = 0.45 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.45 \text{A}/\mu \text{s}$				100	
I _H	holding current	$V_D = 6 \text{ V } R_{GK} = \infty$	$T_{VJ} = 25$ °C			200	mA
	gate controlled delay time		$T_{VJ} = 25 ^{\circ}\text{C}$ $T_{VJ} = 25 ^{\circ}\text{C}$				Î
t _{gd}	gate controlled delay tillle	$V_D = \frac{1}{2} V_{DRM}$				2	με
		$I_G = 0.45 A; di_G/dt = 0.45 A/\mu s$	>				1
t _q	turn-off time	$V_R = 100 \text{ V}; I_T = 150 \text{ A}; V = \frac{2}{3}$	/ \/ T 400.00		150		μs



Package TO-240AA			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
RMS	RMS current	per terminal					200	Α
T _{vJ}	virtual junction temperature				-40		125	°C
Top	operation temperature				-40		100	°C
T _{stg}	storage temperature				-40		125	°C
Weight						81		g
M _D	mounting torque				2.5		4	Nm
$\mathbf{M}_{_{T}}$	terminal torque				2.5		4	Nm
d _{Spp/App}	creepage distance on surface	striking distance through air	terminal to terminal 13.0 terminal to backside 16.0		9.7			mm
$d_{\text{Spb/Apb}}$	creepage distance on surface	Striking distance through an			16.0			mm
V _{ISOL}	isolation voltage	t = 1 second			3600			٧
.002	t = 1 minute		50/60 Hz, RMS; IISOL ≤ 1 mA		3000			٧



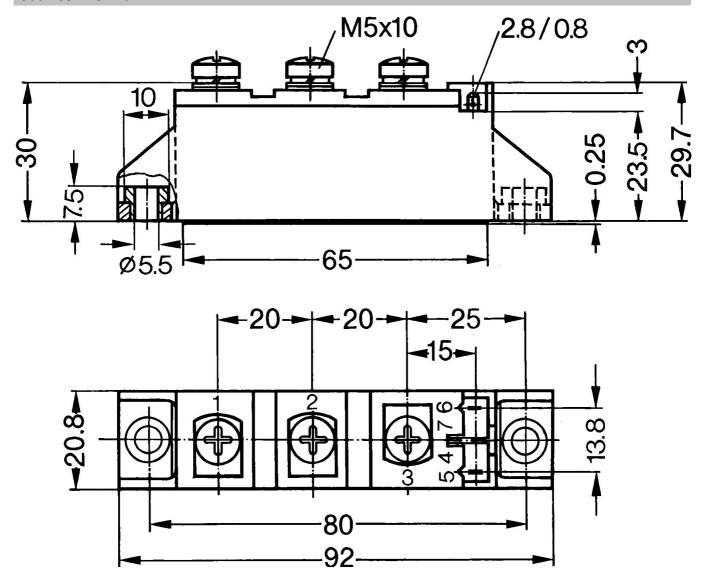
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCC56-08io8B	MCC56-08io8B	Box	36	457566

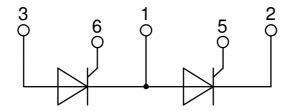
Similar Part	Package	Voltage class
MCMA65P1200TA	TO-240AA-1B	1200
MCMA85P1200TA	TO-240AA-1B	1200

Equiva	alent Circuits for	Simulation	* on die level	T _{vJ} = 125 °C
$I \rightarrow V_0$)—[R ₀]-	Thyristor		
V _{0 max}	threshold voltage	0.85		V
$R_{0 \text{ max}}$	slope resistance *	2.5		mΩ



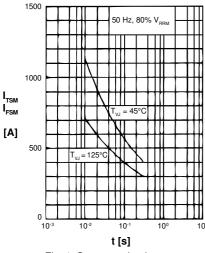
Outlines TO-240AA

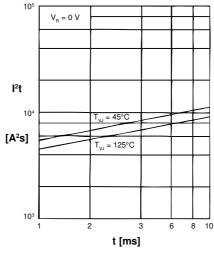






Thyristor





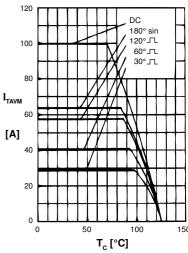
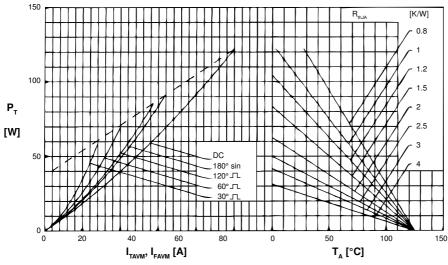


Fig. 1 Surge overload current I_{TSM} , I_{FSM} : Crest value, t: duration

Fig. 2 I2t versus time (1-10 ms)

Fig. 3 Maximum forward current at case temperature



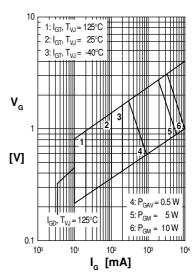
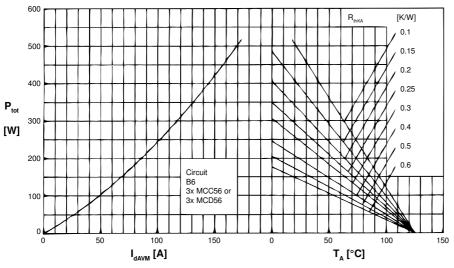


Fig. 4 Power dissipation vs. onstate current and ambient temperature (per thyristor/diode)

Fig. 5 Gate trigger charact.



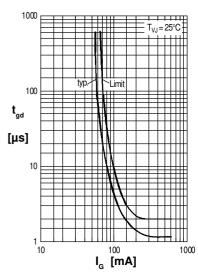


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

Fig. 7 Gate trigger delay time



Thyristor

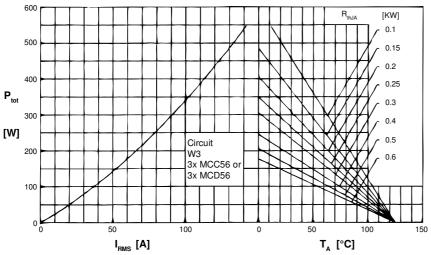


Fig. 8 Three phase AC-controller: Power dissipation vs. RMS output current and ambient temperature

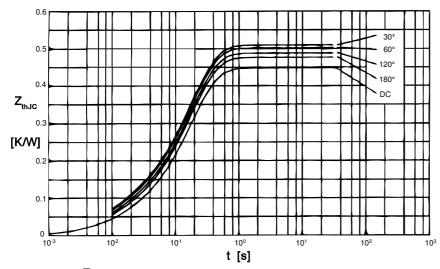


Fig. 9 Transient thermal impedance junction to case (per thyristor)

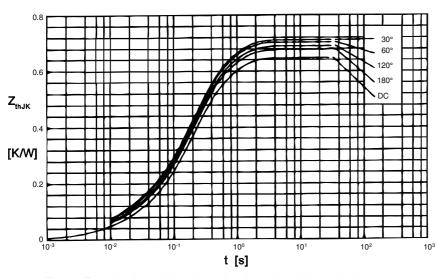


Fig. 10 Transient thermal impedance junction to heatsink (per thyristor)

 R_{thJC} for various conduction angles d:

hJC -	
d	R _{thJC} [K/V
DC	0.450
180°	0.470
120°	0.490
60°	0.505
30°	0.520

Constants for Z_{thJC} calculation:

i	R _{thi} [K/W]	t, [s]			
1	0.014	0.0150			
2	0.026	0.0095			
3	0.410	0.1750			

 R_{thJK} for various conduction angles d:

d	R _{thJK} [K/W
DC	0.650
180°	0.670
120°	0.690
60°	0.705
30°	0.720

Constants for $\mathbf{Z}_{_{\text{thJK}}}$ calculation:

i F	R _{thi} [K/W]	t _, [s]
1	0.014	0.0150
2	0.026	0.0095
3	0.410	0.1750
4	0.200	0.6700